

800G Twin-port NDR 2x400Gb/s OSFP to 2x400Gb/s OSFP Passive Copper Splitter Cable

Features

- 800Gb/s to two 400Gb/s data rates
- Based on 100G-PAM4 modulation
- 0.5, 1, 1.5 and 2 meter lengths
- OSFP ends each consume 0.1 Watts
- Operating case temperature 0-70°C
- Hot pluggable
- RoHS compliant
- polyvinylchloride (PVC) jacket
- LF (Lead Free) HF (Halogen Free) PCB
- CMIS compliant I2C management interface (OSFP end)

Applications

• Quantum-2 InfiniBand or Spectrum-4 Ethernet switch-to-two 400Gb/s ConnectX-7 OSFP adapters



Description

020112-800G-DACH is an 800Gb/s twin-port OSFP (Octal Small Form- factor Pluggable) to 2x400Gb/s OSFP passive Direct Attach Copper (DAC) dual breakout (aka splitter) cable for 400Gb/s End-to- End Infiniband and Ethernet solutions. It has identical design and internals as the QSFP112 version, only with different connector shells. The DAC firmware supports both InfiniBand and Ethernet and is automatically enabled depending on the protocol of the switch attached to.

The 8-channel twin-port OSFP end uses a finned top form-factor for use in Quantum-2 and Spectrum-4 switch cages. The two 400G ends support 4-channels of 100G-PAM4 (400G) and use a flat top OSFP for use in ConnectX-7 adapters using riding heat sinks on the connector cage.

DAC cables are the lowest-cost, lowest-latency, near zero power consuming, high-speed links available due to their simplicity of design and minimal components. The "passive" term refers to the copper cable containing no electronics in the data path. Each end includes an EEPROM which provides product identification and characteristics to the host system. Every cable length is tuned to reduce internal signal noise and back reflections. Thin 30AWG is used for 1 and 1.5-meter lengths and thicker 26AWG for 2 to 3-meters.

Main use is linking an 800Gb/s Quantum-2 switch or Spectrum-4 switch to OSFP-based 400Gb/s ConnectX-7 PCIe network adapter cards.

NADDOD's cable solutions provide power-efficient connectivity enabling higher port bandwidth, density and configurability at a low cost and reduced power requirement in the data centers. Rigorous cable production testing ensures best out-of-the-box installation experience, performance, and durability.

Absolute Maximum Specifications

Absolute maximum ratings are those beyond which damage to the device may occur.

Between the operational specifications and absolute maximum ratings, prolonged operation is not intended and permanent device degradation may occur.

Table1-Absolute Maximum Specifications						
Parameter	Min.	Typical	Max.	Unit	Note	
Supply voltage	-0.3		3.6	V		
Data Input Voltage	-0.3		3.6	V		
Control Input Voltage	-0.3		3.6	V		

Environmental Specifications

This table shows the environmental specifications for the product

Table2-Environmental Specifications					
Parameter	Min	Typical	Max.	Units	
Storage Temperature	-40		85	°C	



Operational Specifications

Table3-Optical Specifications					
Parameter	Min.	Typical	Max.	Unit	Note
Supply Voltage (Vcc)	3.135	3.3	3.465	V	
Power Consumption			0.1	W	
Operating Case Temperature	0		70	°C	
Operating Relative Humidity	5		85	%	

Electrical Performance Requirements

Table4-Electrical Performance Requirements				
Test Items	Test Condition	Specification		
Current		0.5A per contact		
Voltage		30 vDC per contact		
LLCR	EIA 364-23, 20mVdc, 100mA	less than 2 ohms.		
Continuity	Verify the continuous electrical path	No open, short, or high resistance.		

SI Requirements

Table5-SI Requirements					
Test Items	Specification	Notes			
	≤19.75 dB Min. @26.56 GHz;	From 0.01 GHz to 26.56GHz			
SDD21&SDD12	≥ 11.0 dB max. @26.56GHz;				
ERL	Minimum cable assembly ERL(*) : \geq 8.25dB				
SCD12-SDD12	≥ 10 0.05GHz≤f<12.89GHz				
SCD21-SDD21	≥ 14-0.3108f 12.89GHz≤f≤40GHz	(up to 40GHz)			

Mechanical Performance Requirements

Table6-Mechanical Performance Requirements					
Test Items	Test Condition	Specification			
Mating Forces	A rate of 10mm per minute	OSFP<40N			
Un-mating Forces	A rate of 10mm per minute	OSFP<30N			
Latch strength	Pull to separate module from cage,Test with connector, cage & module (latch engaged)	Minimum of an 125N force			
Bulk cable retention	Pull to separate bulk cable from	Minimum of an 90N force			



in module	module,Test with cable assembly only	
	Flex cable 180° for 10 cycles at X/Y axis,	
Wire Flex	20 times/minutes, with an 1kg suspended	No microsecond discontinuities are allowed.
	weight. Type C EIA 364-41, test condition I.	
Durability	Perform 50 unplug/plug cycles	No evidence of physical damage
Cable Minimum	The cable is bent on time over the correct	
Bend Radius	mandrel with 5 perpendicular, the	No physical damage, Verify continuity and SI
Benu Raulus	Minimum bendRadius is 10x OD.	

Mechanical Specifications

Table7-Mechanical Specifications						
Parameter	Value		Units			
Diameter	30AWG	mm				
Diameter	28AWG					
Longth tolorance	length < 2 m ±25		mm			
Length tolerance	length ≥ 2 m	±50	mm			

Minimum Bend Radius

Table8-Minimum Bend Radius

Tableo Filininani Bena Kaalas		
OPN	Length (m)	AWG (mm)
020112-800G-CU0-5H	0.50	30AWG, 2x8pairs
020112-800G-CU1H	1.0	28AWG, 2x8pairs
020112-800G-CU1-5H	1.5	28AWG, 2x8pairs
020112-800G-CU2H	2.0	28AWG, 2x8pairs

Note:

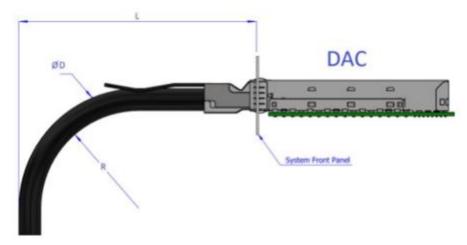
The minimum assembly bending radius (close to the connector) is 10x the cable's outer diameter. The repeated bend (far from the connector) is also 10x the cable's outer diameter. The single bend (far from the connector) is 5x the cable's outer diameter.

**Combined end' is the 'head' where the cables join together, inserted into the switch. 'Single end' is the 'tail' which plugs into the HCA/NIC in a server.

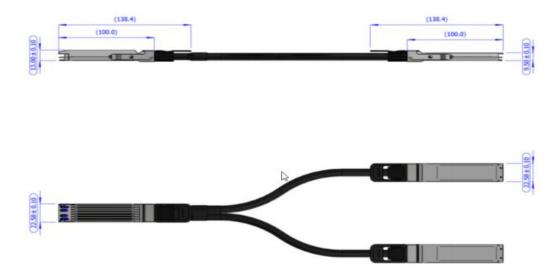
L = Assembly Space. Minimum value depends on the backshell (connector housing) dimensions = the space for the cable assembly behind the rack door.



Assembly Bending Radius



Mechanical Dimensions



Pin Description

The device is OSFP MSA Specification for OSFP Octal Small Form Factor Pluggable Module Rev. 1.12 compliant, see www.osfpmsa.org.

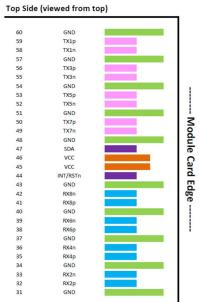
Table9	Table9-Pin Description						
Pin	Symbol	Description	Pin	Symbol	Description		
1	GND	Ground	31	GND	Ground		
2	Tx2p	Transmitter Non-Inverted Data Input	32	Rx2p	Receiver Non-Inverted Data Output		
3	Tx2n	Transmitter Inverted Data Input	33	Rx2n	Receiver Inverted Data Output		

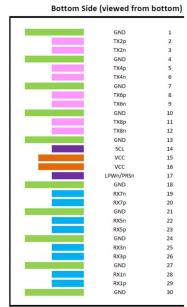


4	GND	Ground	34	GND	Grounds
5	Tx4p	Transmitter Non-Inverted Data Input	35	Rx4p	Receiver Non-Inverted Data
					Output
6	Tx4n	Transmitter Inverted Data Input	36	Rx4n	Receiver Inverted Data Output
7	GND	Ground	37	GND	Ground
8	Тх6р	Transmitter Non-Inverted Data Input	38	Rx6p	Receiver Non-Inverted Data
					Output
9	Tx6n	Transmitter Inverted Data Input	39	Rx6n	Receiver Inverted Data Output
10	GND	Ground	40	GND	Ground
11	Tx8p	Transmitter Non-Inverted	41	Rx8p	Receiver Non-Inverted Data
		Data input			Output
12	Tx8n	Transmitter Inverted Data Input	42	Rx8n	Receiver Inverted Data Output
13	GND	Ground	43	GND	Ground
14	SCL	2-wire serial interface clock	44	INT / RSTn	Module Interrupt / Module
					Reset
15	VCC	+3.3V Power	45	VCC	+3.3V Power
16	VCC	+3.3V Power	46	VCC	+3.3V Power
17	LPWn /	Low-Power Mode / Module	47	SDA	2-wire Serial interface data
	PRSn	Present			
18	GND	Ground	48	GND	Ground
19	Rx7n	Receiver Inverted Data Output	49	Tx7n	Transmitter Inverted Data Input
20	Rx7p	Receiver Non-Inverted Data Output	50	Tx7p	Transmitter Non-Inverted Data
					Input
21	GND	Ground	51	GND	Ground
22	Rx5n	Receiver Inverted Data Output	52	Tx5n	Transmitter Inverted Data Input
23	Rx5p	Receiver Non-Inverted Data Output	53	Tx5p	Transmitter Non-Inverted Data
					Input
24	GND	Ground	54	GND	Ground
25	Rx3n	Receiver Inverted Data Output	55	Tx3n	Transmitter Inverted Data Input
26	Rx3p	Receiver Non-Inverted Data Output	56	Тх3р	Transmitter Non-Inverted Data
					Input
27	GND	Ground	57	GND	Ground
28	Rx1n	Receiver Inverted Data Output	58	Tx1n	Transmitter Inverted Data Input
29	Rx1p	Receiver Non-Inverted Data Output	59	Tx1p	Transmitter Non-Inverted Data
					Input
30	GND	Ground	60	GND	Ground



OSFP Module Pad Layout





Materials

Connector

- The Backshell material is Nickel Plated Zinc
- The PCB has gold plated pads
- All materials are RoHS complaint
- The PCBs are certified by UL

Cable

- The conductors are solid copper with silver plating
- The dielectric consist of BizLinkZELL® (Skin Foam Skin PE)
- The cable jacket is polyvinylchloride (PVC) .
- All materials are RoHS complaint
- The cables are UL listed CL2 75°C

Ordering Information

Table10-Ordering Information	
PN	Description
020112-800G-CU0-5H	passive copper splitter cable, InfiniBand 800Gb/s to 2x 400Gb/s, OSFP to 2x OSFP, 0.5m
020112-800G-CU1H	passive copper splitter cable, InfiniBand 800Gb/s to 2x 400Gb/s, OSFP to 2x OSFP, 1m
020112-800G-CU1-5H	passive copper splitter cable, InfiniBand 800Gb/s to 2x 400Gb/s, OSFP to 2x OSFP, 1.5m
020112-800G-CU2H	passive copper splitter cable, InfiniBand 800Gb/s to 2x 400Gb/s, OSFP to 2x OSFP, 2m



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